

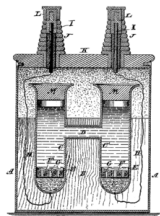
Review of Sub-1-V Bandgap Reference

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03/05/2024

- Extremely important:
 - Bias circuits, signal conditioning, power regulation, VCO ...
- After the 1950s, Zener diodes began to replace the Weston standard cell [1, 2]
 - Miniaturized, but reduced lifetime [3]
- Manufacturing advancements led to highly-doped pn junctions, reducing their temperature dependence [4]
- The bandgap reference circuit leverages additional device properties to render the output voltage a function of only the material bandgap



Basic Bandgap Theory

PN Junction

- Current is related to V_f , which is linearly dependent on temperature
- The saturation current can be shown by approximating the temperature dependence of n_i [5]
- Normally, PN junctions don't behave this way due to surface effects & depletion region generation / recombination [6]
- This *does* nicely describe the workings of a BJT

$$V_T = \frac{kT}{q} \approx 8.617 \times 10^{-5} \text{ V/K} \quad (1)$$

$$I = I_s \left[\exp\left(\frac{V_f}{V_T}\right) - 1 \right] \quad (2)$$

$$n_i^2 = C_0 T^3 \exp\left(\frac{-E_G}{kT}\right)$$
$$I_s \simeq C_{p+n,p} T^{\beta_{p,n}} \exp\left(\frac{-E_G}{kT}\right) \quad (3)$$

- Performing a Taylor series expansion on the formula for V_{BE} as a function of I_C yields this mess:

$$V_{BE} = \frac{kT_0}{q} \left\{ \ln\left(\frac{I_C}{I_S T_0}\right) + \left[\ln\left(\frac{I_C}{I_S T_0}\right) - \left(\beta + \frac{E_{G0}}{kT_0}\right) \right] \left(\frac{T}{T_0} - 1\right) - \frac{\beta}{2} \left(\frac{T}{T_0} - 1\right)^2 + \dots + \frac{\beta(-1)^{(n-1)}}{n(n-1)} \left(\frac{T}{T_0} - 1\right)^n + \dots \right\}$$

$V_{BE} > 4V_T, \quad T < 2T_0$

which neatly shows that as doping concentration increases, temperature dependence decreases [7]

- It is possible to choose a ratio of devices Θ to compensate this thermal relationship

$$\Theta = r \ln\left(\frac{I_{C2}}{I_{S2} T_0}\right) - m \ln\left(\frac{I_{C1}}{I_{S1} T_0}\right) \quad (4)$$

Basic Bandgap Theory

Thermal Compensation

- By properly selecting Θ , the first order temperature dependence of current density is eliminated
- Since E_{G_0} is much greater than ΦV_{T_0} , V_{ref} becomes primarily a function of the bandgap
- In a standard bandgap core, the temperature coefficient of $V_{BE} = -2 \text{ mV}/^\circ\text{C}$ is cancelled by the ΔV_{BE} from the current density ratio [8, 9]

$$\Delta V_{BE} = V_T \ln \left(\frac{I_{C_2}}{I_{C_1}} \right), \quad I_C = I_{C_0} \left(\frac{T}{T_0} \right)$$
$$\Delta V_{BE} = V_T \ln \left(\frac{T_0}{T} \right) \quad (5)$$

Basic Bandgap Theory

Limitations

- Many designs like those of Widlar, Kuijk, and Brokaw enhance the performance with additional error amplification and series regulation
- With $E_{G_{Si}} = 1.12$ eV, standard bandgap topologies have a lower limit around 1.25 V, dependent on the threshold voltage of the devices used for its construction [10]

$$V_{ref} = V_{f1} + \frac{R_2}{R_3} V_T \ln\left(\frac{R_2}{R_1} N\right) \quad (6)$$

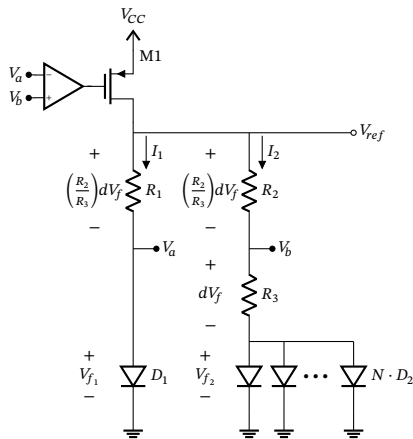
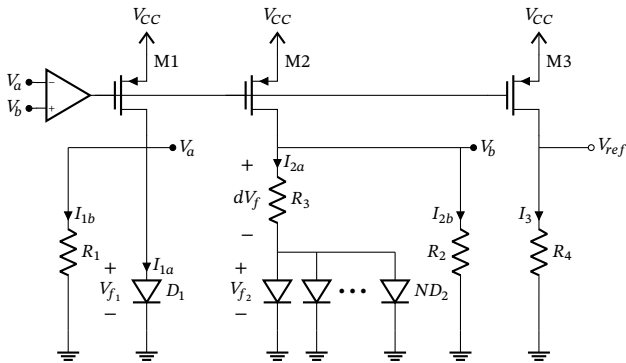


Figure 1: Conventional bandgap reference circuit schematic used for comparison. Redrawn from [11].

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- $$\begin{aligned} V_{ref,old} &= V_{f_1} + \frac{R_2}{R_3} V_T \ln\left(\frac{R_2}{R_1} N\right) \\ V_{ref,new} &= \frac{R_4}{R_2} V_{f_1} + \frac{R_4}{R_3} V_T \ln(N) \end{aligned} \quad (7)$$



They did not manage to achieve operation under 1 V V_{CC} !

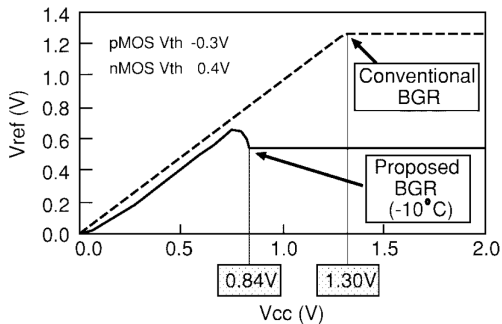


Figure 3: What they expected.

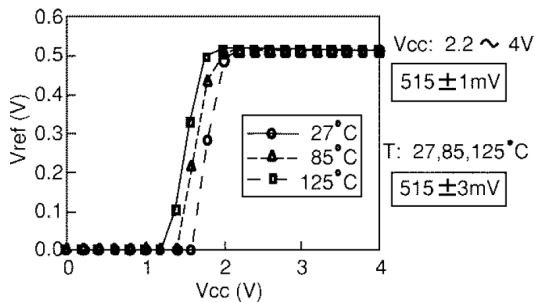


Figure 4: What they got.

Their Results

What Happened?

- Authors worked at Toshiba
- A 400 nm flash memory process was selected with very high threshold voltages
- This prevented their design from even turning on before 1 V V_{CC} , which they claimed operation under
- Native NMOS devices were used at the inputs of the op-amp to compensate for the poor threshold voltages
- Why this choice of fabrication process?

Simulation Process	Unknown Parameters
V_{thp}	-0.3 V
V_{thn}	0.4 V

Table 1: Simulated threshold voltages.

Flash Memory Process	0.4 μ m P-sub CMOS 1 poly, 1 silicide, 2 metal
V_{thp}	-1.0 V
V_{thn}	0.7 V
$V_{thn,nat}$	-0.2 V

Table 2: Fabricated threshold voltages.

Their Results

Significance

- Papers have collectively been cited over 800 times
- Obvious impact on the industry despite poor hardware results
- No real follow-up work from the authors
- PSRR was not reported
- In reporting distributions, the conventional design had 34 data points, whereas the new design only had 23
- Process parameters for the BJT devices may also have been useful



- Verify performance in a process designed for low voltage operation
- Use same number of data points for design comparison
- Low-tempco thin film resistors, trimmed resistors & BJTs [12, 13, 14]
- Substitute resistors with MOS devices [15]

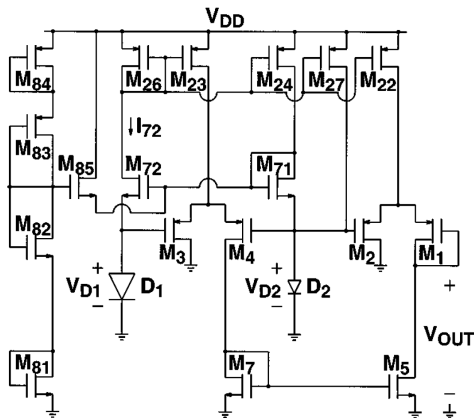


Figure 5: Schematic of resistorless bandgap circuit proposed in [15].

- A group from the University of Pisa proposed a design in 2021 for supply volages down to 0.5 [16]
- Uses a “classic” all-CMOS bandgap core modified with low threshold and native devices in a 0.18 μm process
- Combined with a switched-cap integrator for offset cancellation and low-frequency noise reduction
- $V_{ref} = 220 \text{ mV}$ with sensitivity of $45 \text{ ppm}/^\circ\text{C}$ with current draw of 630 nA
- Considerable performance analysis shown in the paper

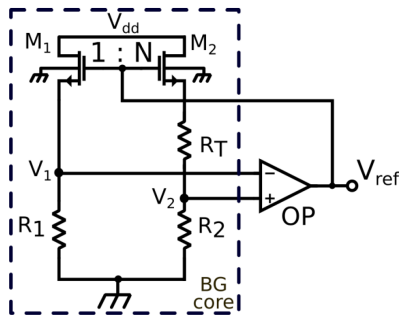


Figure 6: Schematic of all-CMOS design proposed in [16].

- Banba's design was constructed in the Cādence gpdk45_v5.0 to see its performance in a process that was designed for low voltage operation
- Its performance was compared with the stated conventional design, using the same device parameters
- All 1 V-LVT devices were used

gpdk45_v5.0	45 nm 1 s, 1 p, 11 m
V_{thp}	-0.34 V
V_{thn}	0.28 V

Table 3: 1 V-LVT threshold voltages, around the sizes simulated.

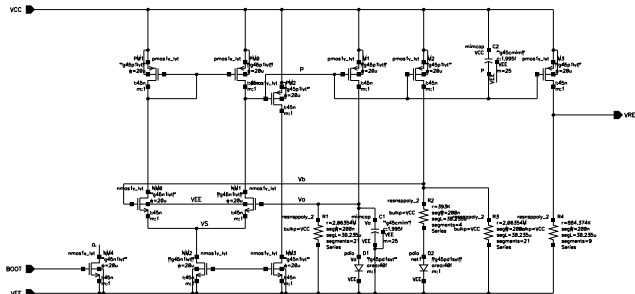
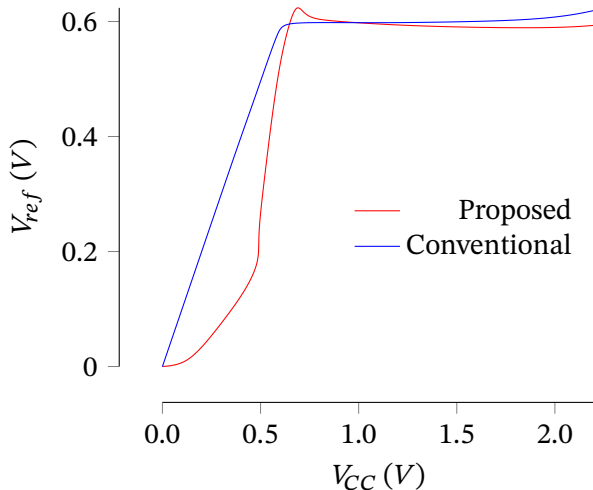


Figure 7: Schematic of the new bandgap as simulated in Cādence Virtuoso. Device sizing as suggested by Razavi, scaled for $l = 45$ nm [17].

- Operation down to about 0.7 V was achieved for both designs
- Shows the device dependence on the threshold voltage
- Proposed design is able to achieve much lower V_{ref} and lower temperature variation
- Startup behavior for the proposed design was consistently slower
- Often showed less stability in operating range
 - Could be due to lack of optimization and poor startup circuit implementation



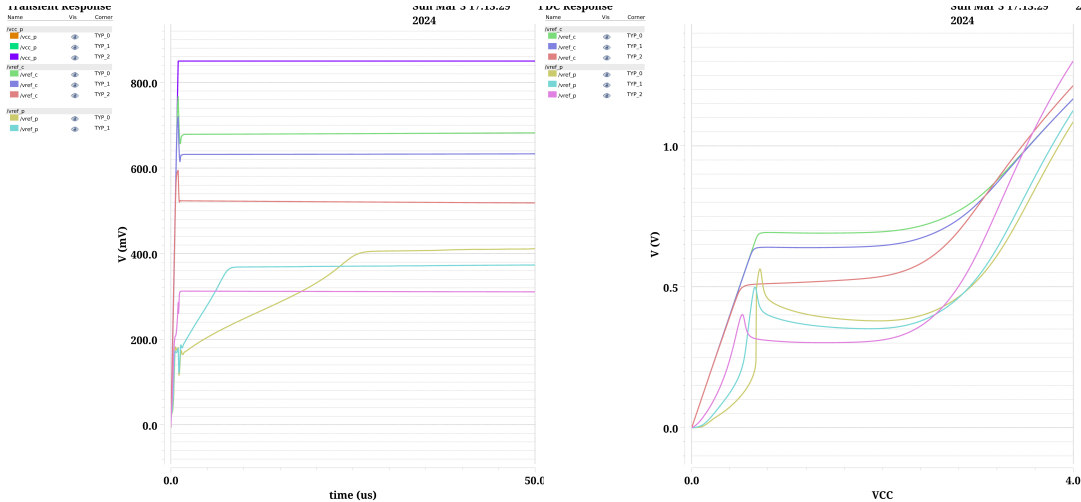


Figure 9: Simulated results over 0, 27, and 100 °C, transient and DC.

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